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IN THE CLAIMS

B1 1 (currently amended). A thermal transfer device comprising a thermal source maintained in parallel to a thermal sink and having a thermally conductive, compressible, multiple turn coil between the thermal source and the thermal sink.

2 (previously amended). The thermal transfer device according to claim 1 wherein the thermal sink surrounds the thermal source.

3 (previously amended). The thermal transfer device according to claim 1 wherein said thermal source is made of a dielectric material.

4 (previously amended). The thermal transfer device according to claim 1 wherein said thermal sink is made of a dielectric material.

6 (previously amended). The thermal transfer device according to claim 1 wherein said thermally conductive coil is made of copper.

7 (previously amended). The thermal transfer device according to claim 6 wherein said copper coil is made from copper wire about 0.011 inch thick.

8 (previously amended). The thermal transfer device according to claim 1 wherein the thermal source and the thermal sink are

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concentric.

9 (currently amended). The thermal transfer device according to claim 8 wherein ~~the~~ a surface of the thermal sink facing the thermal source is grooved to accommodate the ~~compressive~~ compressible coil.

10 (previously amended). The thermal transfer device according to claim 2 wherein the thermal sink includes a means of cooling.

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cut
11 (currently amended). The thermal transfer device according to claim 1 wherein the conductive, compressible, multiple turn coil fills the a space between the thermal source and the thermal sink.

12 (previously amended). In a vacuum chamber comprising a processing chamber including a substrate to be processed, and a processing gas inlet source that traverses a microwave energy source for forming a plasma from a processing gas, the improvement comprising

a microwave impervious gas inlet made of a dielectric material in the form of a tube that provides a thermal source, the dielectric tube surrounded by a concentric dielectric tube that provides a thermal sink, and a compressible, conductive multiple turn coil between the thermal source and the thermal

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sink.

13 (original). The vacuum chamber according to claim 12 wherein said coil is made of copper.

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at 14 (original). The vacuum chamber according to claim 12 wherein said gas inlet source is made of sapphire.
